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Attorney Docket Number
8073-051

MRD 10/28/99

TO THE HONORABLE COMMISSIONER OF PATENTS AND TRADEMARKS
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Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Bok Nam SONG

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other _____Execution Date: October 19, 1999

2. Name and address of receiving party(ies):

Name: Hyundai Electronics Industries Co., Ltd.Address: San 136-1, Ami-Ri, Bubal-Uep, Ichon-Shi, Kyungki-DoCountry (if other than USA): Korea4. Application number(s) or patent number(s): 09/428983If this document is being filed together with a new application, the execution date of the application is: October 19, 1999

A. Patent Application No.(s) _____

B. Patent No.(s) _____

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

PENNIE & EDMONDS LLP
1667 K Street, N.W.
Washington, D.C. 200066. Number of applications and patents involved: 17. Total fee (37 CFR 3.41):.....\$ 40.00
Please charge to the deposit account listed in Section 8.8. Deposit account number:
16-1150

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9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*Harry C. Jones, III20,280

Signature

Name of Person Signing Reg. No.

October 28, 1999

Date

Total number of pages including cover sheet:

2

Mail documents to be recorded with required cover sheet information to:
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/04/1999 DNGUYEN 00000313 161150 09428983

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ASSIGNMENT

WHEREAS, as a below named inventor, I, ASSIGNOR, am the original, first and sole inventor if only one name is listed below, or an original, first and joint inventor if plural names are listed below of the invention in

METHOD OF ERASING FLASH MEMORY AND SUBSTRATE VOLTAGE SUPPLY CIRCUIT

for which I have executed an application for a Patent of the United States on _____ and which

☒ is identified by Pennie & Edmonds docket no. _____

☐ is the national phase of PCT international application

filed on _____

and amended under PCT Article 19 on _____ (if applicable)

☐ was filed in the United States on _____, as Application No. _____

and WHEREAS, **HYUNDAI ELECTRONICS INDUSTRIES CO., LTD., San 136-1, Ami-Ri, Bubal-Uep, Ichon-Shi, Kyungki-Do, Korea**, ASSIGNEES, is desirous of obtaining the entire right, title and interest in, to and under the said invention and said application in the United States:

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to me in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, I, ASSIGNOR, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the ASSIGNEE, its successors, legal representatives and assigns, for the territory of the United States of America, and not elsewhere, the entire right, title and interest in, to and under said United States application and said invention as fully set forth and described therein, and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues, reexamination certificates and extensions thereof; together with the right to file said application in the United States and the right to claim for the same the priority rights derived from any earlier filed application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement, as may be applicable:

AND I, ASSIGNOR, HEREBY authorize and request the Commissioner of Patents and Trademarks of the United States to issue said application to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I, ASSIGNOR, HEREBY covenant and agree that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

AND I, ASSIGNOR, HEREBY further covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and applications and reexamination papers, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in the United States.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

1. Bok Nam SONG
Inventor (print name)

B. D. Song
Inventor (signature)

October 19, 1999
(Date)

Address: Hyundai Apartment 107-806, Sadong-Ri, Daewoul-Myun, Ichon-Shi, Kyungki-Do, KOREA

Mun Jin PARK
Witness (name)

Park mun jin
Witness (signature)

October 19, 1999
(Date)

Jin Seok KIM
Witness (name)

J. S. K.
Witness (signature)

October 19, 1999
(Date)